

Data sheet	
status	Product specification
date of issue	June 1990

# FCB61C65(L/LL)

## 8 K x 8 Fast CMOS low-power static RAM

FOR DETAILED INFORMATION SEE RELEVANT DATA BOOK OR DATA SHEET

### FEATURES

- Operating supply voltage  
5 V ± 10%
- Inputs and outputs ESD protected
- Automatic power-down after a completed read access
- Access time: 55 ns and 70 ns
- Low current consumption:
 

active	70 mA max.
standby (TTL)	3 mA max.
standby (CMOS)	100 µA max. (L-version)
standby (CMOS)	1 µA max. (LL-version)
- Suitable for battery back-up operation: (FCB61C65L/LL only)
 

data retention voltage	2 V min.
data retention current	50 µA max. (L-version)
data retention current	1 µA max. (LL-version)
- Latched data outputs giving stable data between consecutive accesses
- Easy memory expansion
- Common data I/O interface
- All inputs and outputs TTL and CMOS compatible
- All inputs have a Schmitt trigger switching action
- Three-state outputs
- Operating temperature 0 °C to +70 °C

### GENERAL DESCRIPTION

The FCB61C65(L/LL) is a 65536-bit fast, low-power, static random access memory organized as 8192 words of 8 bits each.

The chip enable inputs  $\overline{CE}1$  and  $CE2$  are available for memory expansion and to control the low-power/standby mode.

The device operates from a 5 V power supply and has an access time of 55 ns and 70 ns.

The FCB61C65(L/LL) is ideally suited for memory applications where fast access time, low power and ease of use are required.

The FCB61C65(L/LL) is a CMOS device which uses a 6 transistor memory cell.

The IC is fabricated in a CMOS double-metal single-poly process using ion-implanted silicon gate technology.

### ORDERING AND PACKAGE INFORMATION

EXTENDED TYPE NUMBER	PACKAGE			
	PINS	PIN POSITION	MATERIAL	CODE
FCB61C65 (L/LL)-XXP	28	DIL (600 mil)	plastic	SOT117
FCB61C65 (L/LL)-XXT	28	SO28XL (330 mil)	plastic	SOT213

# 8 K x 8 Fast CMOS low-power static RAM

# FCB61C65(L/LL)

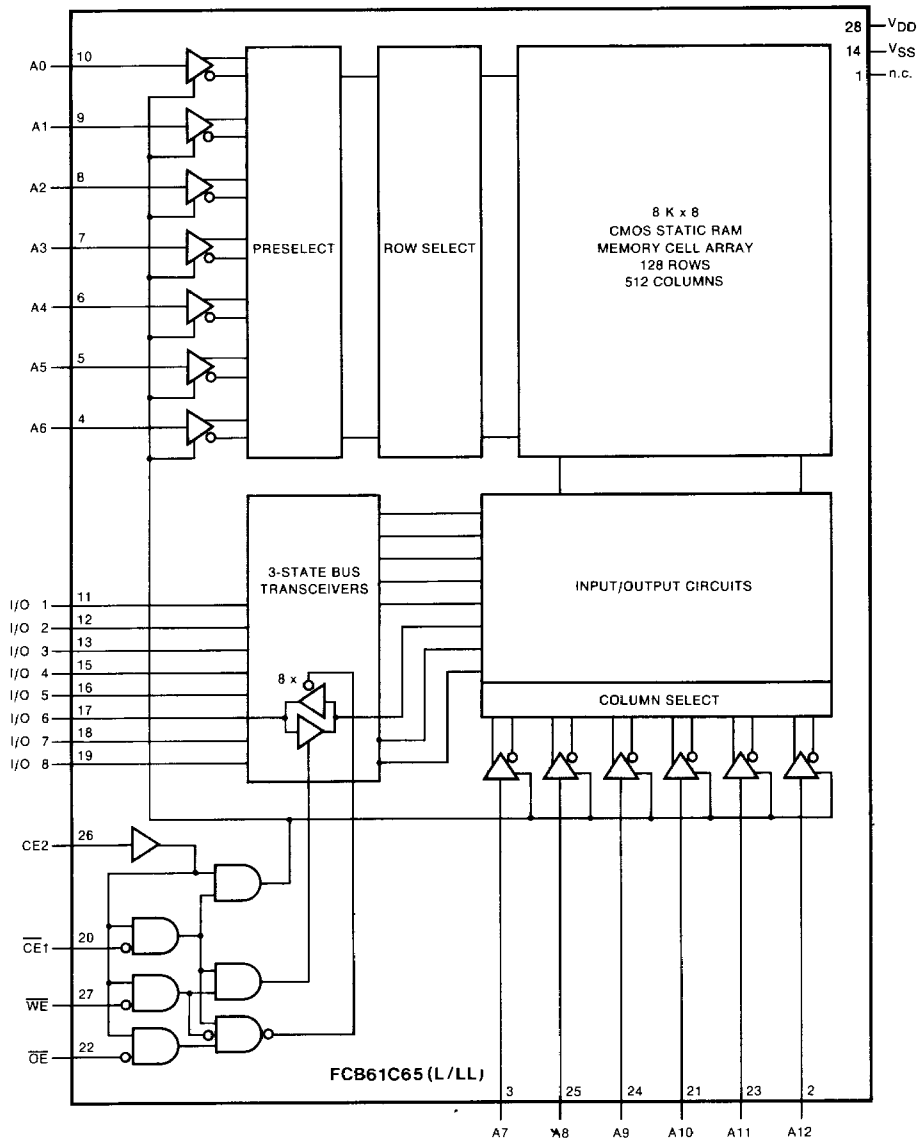


Fig.1 Block diagram.

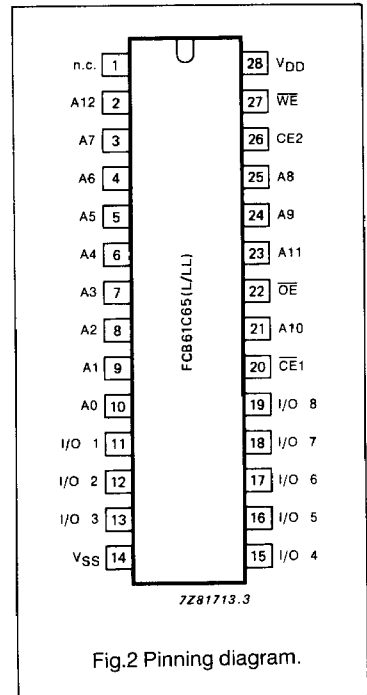
**8 K x 8 Fast CMOS low-power static RAM****FCB61C65(L/LL)****TRUTH TABLE**

CE1	CE2	OE	WE	MODE	I <sub>DD</sub>	I/O PIN	REF. CYCLE
H	X	X	X	not selected	I <sub>SB</sub> *	HIGH Z	
X	L	-X	X	not selected	I <sub>SB</sub> *	HIGH Z	
L	H	L	H	read	I <sub>DD</sub> /I <sub>DD1</sub> *	D OUT	read
L	H	H	L	write	I <sub>DD</sub>	D IN	write
L	H	L	L	write	I <sub>DD</sub>	D IN	write
L	H	H	H	ready-read	I <sub>DD</sub> /I <sub>DD1</sub> *	HIGH Z	

\* Including L/LL versions if input levels are CMOS.

**PINNING**

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
A12	2	address input
A7 to A0	3 to 10	address inputs
I/O 1 to I/O 3	11 to 13	data inputs/outputs
V <sub>SS</sub>	14	ground
I/O 4 to I/O 8	15 to 19	data inputs/outputs
CE1	20	chip enable 1
A10	21	address input
OE	22	output enable
A11, A9, A8	23 to 25	address inputs
CE2	26	chip enable 2
WE	27	write enable
V <sub>DD</sub>	28	+5 V supply



**8 K x 8 Fast CMOS low-power static RAM****FCB61C65(L/LL)****DC CHARACTERISTICS**

$V_{DD} = 5 V \pm 10\%$ ;  $T_{amb} = 0$  to  $70\text{ }^{\circ}\text{C}$ . Typical readings taken at  $V_{DD} = 5 V$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ . All voltages are referenced to  $V_{SS}$  (0 V) unless otherwise specified. DC characteristics are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{LI}$	input leakage current	$V_I = V_{SS}$ to $V_{DD}$	-1	-	1	$\mu\text{A}$
$I_{LO}$	output leakage current	$\overline{CE}1$ or $\overline{OE} = V_{IH}$ or $CE2 = V_{IL}$ ; $V_{I/O} = V_{SS}$ to $V_{DD}$	-1	-	1	$\mu\text{A}$
$I_{DD}$	average operating current	cycle time 55 ns; 100% duty factor; note 1 $I_{I/O} = 0\text{ mA}$	-	40	70	mA
$I_{DD}$	average operating current	cycle time 70 ns; 100% duty factor; note 1 $I_{I/O} = 0\text{ mA}$	-	35	60	mA
$I_{DD1}$	DC operating current	$\overline{WE} = V_{IH}$ ; $I_{I/O} = 0\text{ mA}$ ; $f = 0\text{ Hz}$  $\overline{WE} = \text{CMOSH}$ ; $V_I = \text{CMOS}$ ; note 2	-	3	6	mA
$I_{DDL}$	FCB61C65L only		-	2	100	$\mu\text{A}$
$I_{DDLL}$	FCB61C65LL only		-	0.05	1.0	$\mu\text{A}$
$I_{SB}$	standby current	$\overline{CE}1 = V_{IH}$ or $CE2 = V_{IL}$  $\overline{CE}1 = \text{CMOSH}$ and $CE2 = \text{CMOS}$ or $CE2 = \text{CMOSL}$	-	1.5	3.0	mA
$I_{SBL}$	FCB61C65L only		-	2	100	$\mu\text{A}$
$I_{SBL}$	FCB61C65LL only		-	0.05	1.0	$\mu\text{A}$
$V_{OL}$	output voltage LOW	$I_{OL} = 4\text{ mA}$	-	-	0.4	V
$V_{OL}$	output voltage LOW	$I_{OL} = 20\text{ }\mu\text{A}$	-	-	0.2	V
$V_{OH}$	output voltage HIGH	$I_{OH} = -1\text{ mA}$	2.4	-	-	V
$V_{OH}$	output voltage HIGH	$I_{OH} = -20\text{ }\mu\text{A}$	$V_{DD}-0.2$	-	-	V

**Notes to the DC characteristics**

- $I_{DD} \leq 50\text{ mA}$  at a cycle time of 100 ns and  $\leq 45\text{ mA}$  at a cycle time of 120 ns.
- CMOS = CMOSH:  $V_{DD} - 0.2\text{ V} \leq \text{level} \leq V_{DD} + 0.2\text{ V}$  or  
CMOSL:  $-0.2\text{ V} \leq \text{level} \leq +0.2\text{ V}$ .

**CAPACITANCES**

$f = 1\text{ MHz}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$  (parameters in this table are sampled and not 100% tested).

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$C_I$	input capacitance		8	pF
$C_I$	CE1, CE2, WE, OE	$V_I = 0\text{ V}$	7	pF
$C_I$	all other inputs	$V_I = 0\text{ V}$	8	pF
$C_{I/O}$	input/output capacitance	$V_{I/O} = 0\text{ V}$	8	pF

## 8 K x 8 Fast CMOS low-power static RAM

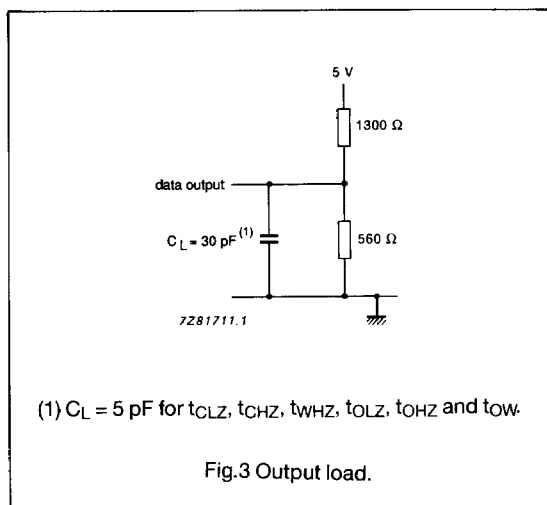
## FCB61C65(L/LL)

## TIMING CHARACTERISTICS

$V_{DD} = 5 V \pm 10\%$ ;  $T_{amb} = 0$  to  $70\text{ }^{\circ}\text{C}$ ; inputs pulse levels = 0.4 to 2.4 V; input rise and fall times = 5 ns; input and output timing reference levels = 1.5 V and output loading as in Figure 3; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	55 TYPE		70 TYPE		UNIT
			MIN.	MAX.	MIN.	MAX.	
<b>Read cycle</b>							
$t_{RC}$	read cycle time		55	-	70	-	ns
$t_{AA}$	address access time		-	55	-	70	ns
$t_{ACE}$	chip enable access time		-	55	-	70	ns
$t_{OE}$	output enable access time		-	30	-	35	ns
$t_{CLZ}$	chip enable to output LOW Z	note 6	5	-	5	-	ns
$t_{OLZ}$	output enable to output LOW Z	note 6	5	-	5	-	ns
$t_{CHZ}$	chip disable to output HIGH Z	note 6	-	30	-	30	ns
$t_{OHZ}$	output disable to output HIGH Z	note 6	-	30	-	30	ns
$t_{OH}$	output hold time		10	-	10	-	ns
<b>Write cycle</b>							
$t_{WC}$	write cycle time		55	-	70	-	ns
$t_{CW}$	chip enable to end of write	note 11	50	-	65	-	ns
$t_{AW}$	address valid to end of write		50	-	65	-	ns
$t_{AS}$	address set up time		0	-	0	-	ns
$t_{WP}$	write pulse width	note 9	30	-	35	-	ns
$t_{WR}$	write recovery time	note 10	0	-	0	-	ns
$t_{WHZ}$	write enable to output HIGH Z	note 16	-	20	-	25	ns
$t_{DW}$	data to write time overlap		25	-	30	-	ns
$t_{DH}$	data hold from write time		5	-	5	-	ns
$t_{ow}$	end of write to output LOW Z	note 16	5	-	5	-	ns

## Output load



8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

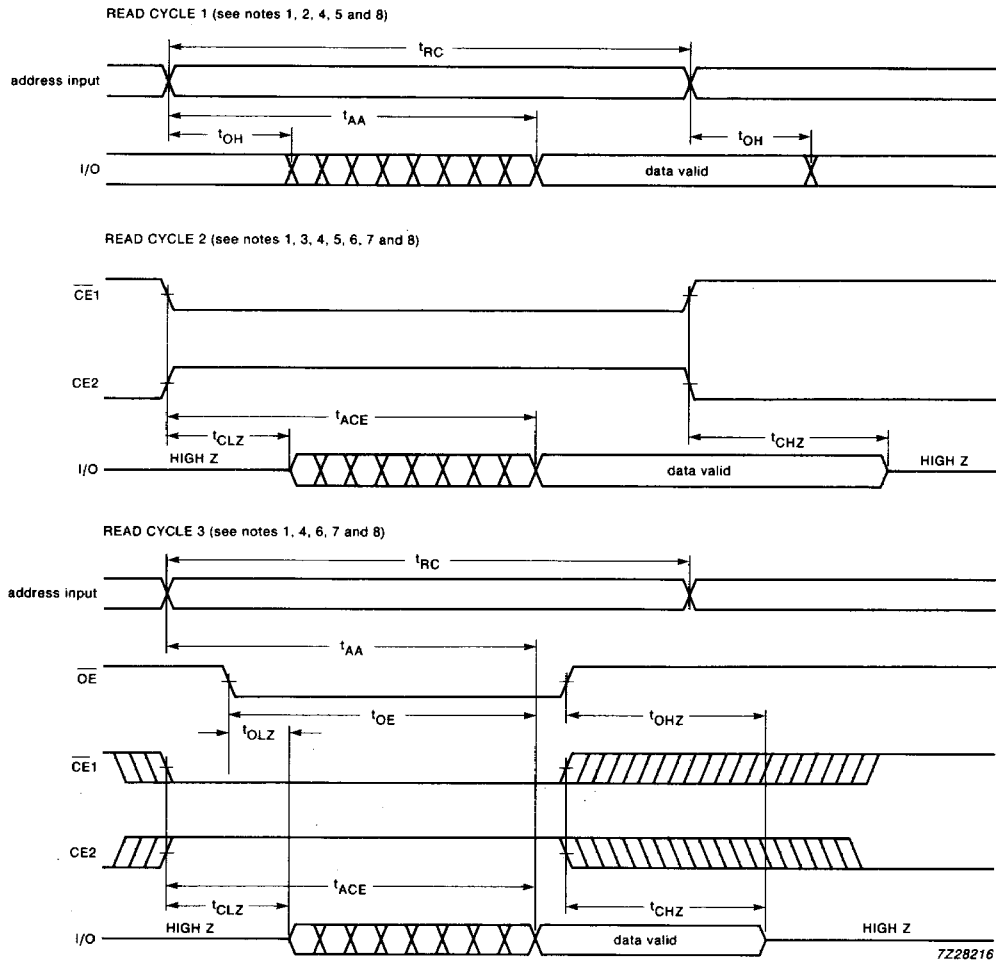


Fig.4 Read cycle timing.

8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

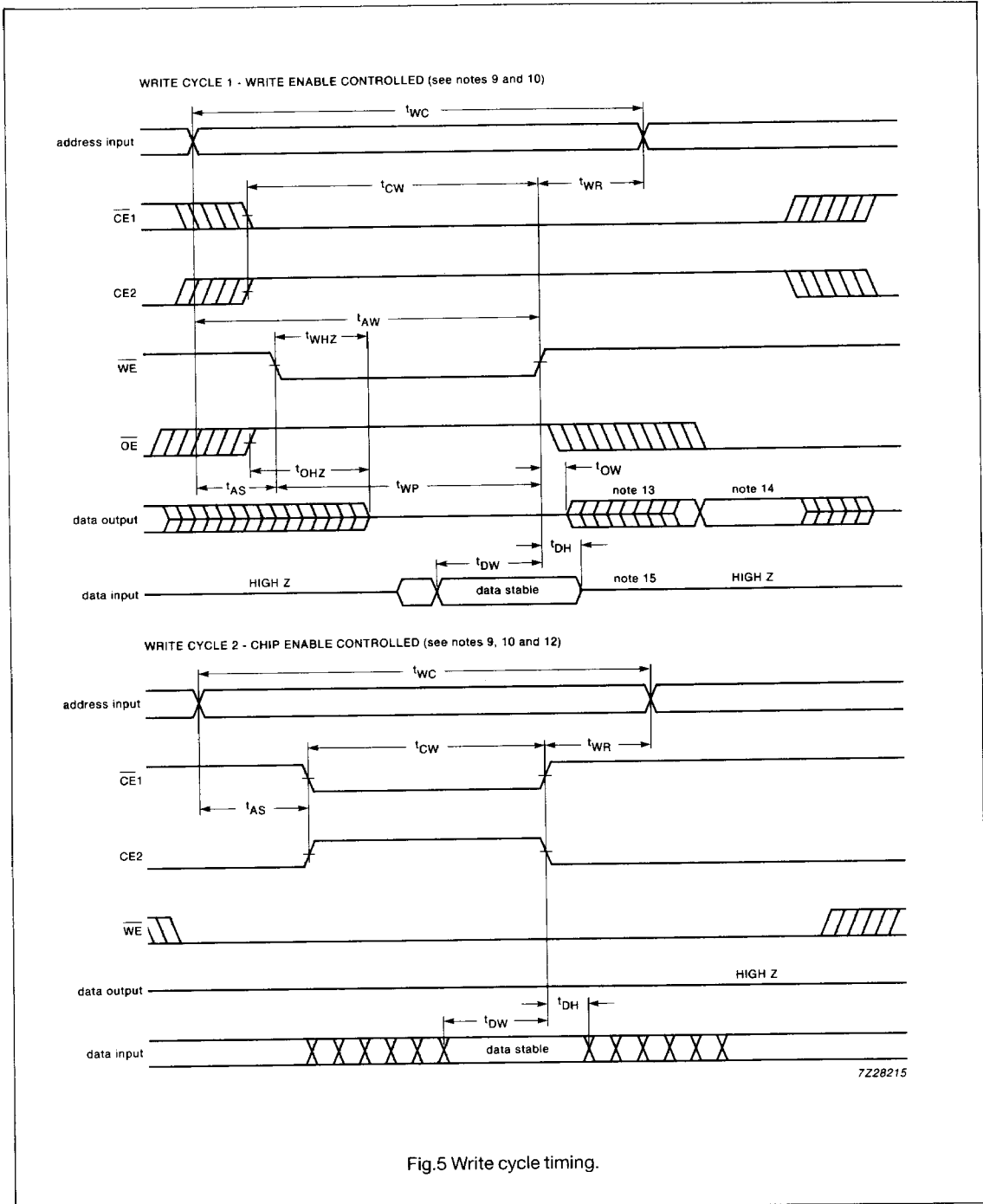


Fig.5 Write cycle timing.

**8 K x 8 Fast CMOS low-power static RAM****FCB61C65(L/LL)**

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**Notes to the timing characteristics****Read cycle** (see Fig.4)

1.  $\overline{WE}$  is HIGH for read cycle.
2. Device is continuously selected,  $\overline{CE1}$  is LOW and CE2 is HIGH.
3. Address is valid prior to or coincident with  $\overline{CE1}$  LOW or CE2 HIGH transition.
4. When  $\overline{CE1}$  is LOW and CE2 HIGH, the address inputs may not be floating.
5.  $\overline{OE}$  is LOW.
6.  $C_L = 5$  pF for  $t_{CLZ}$ ,  $t_{CHZ}$ ,  $t_{OLZ}$ , output transition measured at  $\pm 200$  mV from preceding steady state. These parameters are sampled and not 100% tested.
7.  $t_{CLZ}$  and  $t_{ACE}$  are measured from the last  $\overline{CE1}$  going LOW or CE2 going HIGH.  $t_{CHZ}$  is measured from the first of  $\overline{CE1}$  going HIGH or CE2 going LOW.
8. If D OUT in two consecutive read cycles is the same, D OUT remains stable.

**Write cycle** (see Fig.5)

9. A write occurs during an overlap of LOW  $\overline{CE1}$ , a HIGH CE2 and a LOW  $\overline{WE}$ .
10.  $t_{WR}$  is measured from the earlier of CE2 going to LOW or  $\overline{CE1}$  or  $\overline{WE}$  going HIGH at the end of a write cycle.
11. If the  $\overline{CE1}/CE2$  transition occurs simultaneously to or after the  $\overline{WE}$  LOW transition the outputs remain in a high impedance state.
12.  $\overline{OE}$  is continuously LOW.
13. D OUT is in the same phase as the write data of this write cycle.
14. D OUT is the read data of the next address.
15. If  $\overline{CE1}$  is LOW (CE2 is HIGH) and I/O pins are in the output state during this period then input data signals of opposite phase to the outputs must not be applied.
16.  $C_L = 5$  pF for  $t_{WHZ}$  and  $t_{OW}$ , measured at  $\pm 200$  mV from steady state. These parameters are sampled and not 100% tested.



## 8 K x 8 Fast CMOS low-power static RAM

## FCB61C65(L/LL)

## DATA RETENTION CHARACTERISTICS FOR LOW POWER/STANDBY MODE

(FCB61C65L/LL only)

 $T_{amb} = 0$  to  $+70$  °C;  $I_{DRL/LL}$  measurements are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supply</b>						
$V_{DR}$	supply voltage for data retention	$\overline{CE}1 = \text{CMOSH}$ or $CE2 = \text{CMOSL}$ with other $V_i = \text{CMOS}$ ; note 1	2.0	-	5.5	V
$I_{DRL}$ $I_{DRLl}$	supply current during data retention FCB61C65L only FCB61C65LL only	$V_{DR} = 3$ V; $CE2 = \text{CMOSL}$ ; other $V_i = \text{CMOS}$ or $\overline{CE}1 = \text{CMOSH}$ ; other $V_i = \text{CMOS}$	- -	2 0.05	50 1	$\mu\text{A}$ $\mu\text{A}$
<b>Timing</b>						
$t_{CDR}$	chip disable to data retention time		0	-	-	ns
$t_R$	recovery time to fully active	note 2	$t_{RC}$	-	-	ns

## Notes to the data retention characteristics

- CMOS = CMOSH:  $V_{DR} - 0.2 \text{ V} \leq \text{level} \leq V_{DR} + 0.2 \text{ V}$  or  
CMOSL:  $-0.2 \text{ V} \leq \text{level} \leq +0.2 \text{ V}$ .
- $t_{RC}$  = read cycle time.

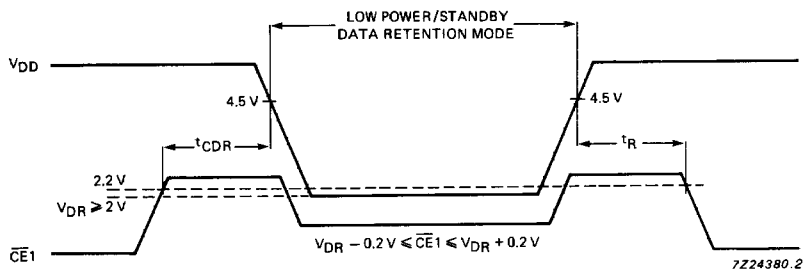
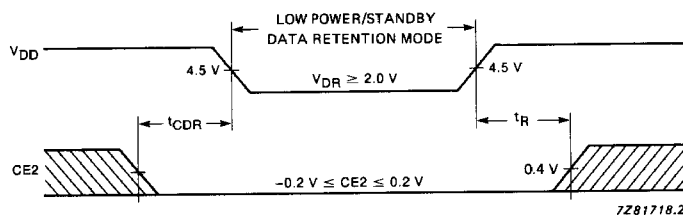
Fig.6 Data retention waveform ( $\overline{CE}1$  controlled).

Fig.7 Data retention waveform (CE2 controlled).

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date of issue	August 1990

# FCF61C65(L/LL)

## 8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FOR DETAILED INFORMATION SEE RELEVANT DATA BOOK OR DATA SHEET

### FEATURES

- Operating supply voltage 5 V ± 10%
- Inputs and outputs ESD protected
- Automatic power-down after a completed read access
- Access time: 85 ns
- Low current consumption:
  - active 60 mA max.
  - standby (TTL) 3 mA max.
  - standby (CMOS) 200 µA max. (L-version)
  - standby (CMOS) 4 µA max. (LL-version)
- Suitable for battery back-up operation: (FCF61C65L/LL only)
  - data retention voltage 2 V min.
  - data retention current 100 µA max. (L-version)
  - data retention current 4 µA max. (LL-version)
- Latched data outputs giving stable data between consecutive accesses
- Easy memory expansion
- Common data I/O interface
- All input and outputs TTL and CMOS compatible
- All inputs have a Schmitt trigger switching action
- Three-state outputs
- Operating temperature -40 °C to +85 °C

### GENERAL DESCRIPTION

The FCF61C65(L/LL) is a 65536-bit, fast, low-power, static random access memory organized as 8192 words of 8 bits each.

The chip enable inputs  $\overline{CE}1$  and  $CE2$  are available for memory expansion and to control the lower-power/standby mode.

The device operates from a 5 V power supply and has an access time of 85 ns.

The FCF61C65(L/LL) is ideally suited for memory applications for the extended temperature range of -40 to +85°C where fast access time, low power and ease of use are required.

The FCF61C65(L/LL) is a full CMOS device using a 6 transistor memory cell.

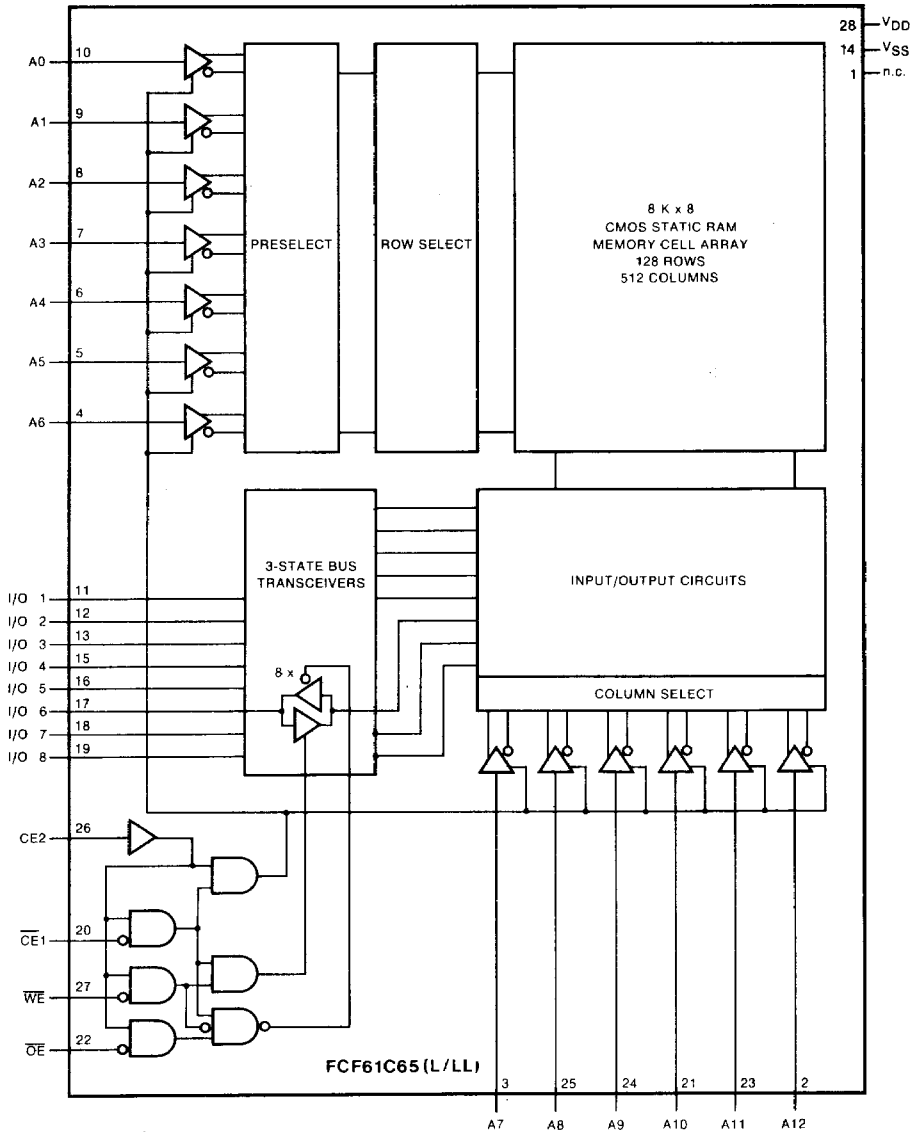
The IC is fabricated in a CMOS double-metal single-poly process using ion-implanted silicon gate technology.

### ORDERING AND PACKAGE INFORMATION

EXTENDED TYPE NUMBER	PACKAGE			
	PINS	PIN POSITION	MATERIAL	CODE
FCF61C65 (L/LL)-85T	28	SO28XL(330mil)	plastic	SOT213

**8 K x 8 Fast CMOS low-power static RAM for extended temperature range**

**FCF61C65(L/LL)**



7Z26566

Fig.1 Block diagram.

# 8 K x 8 Fast CMOS low-power static RAM for extended temperature range

## FCF61C65(L/LL)

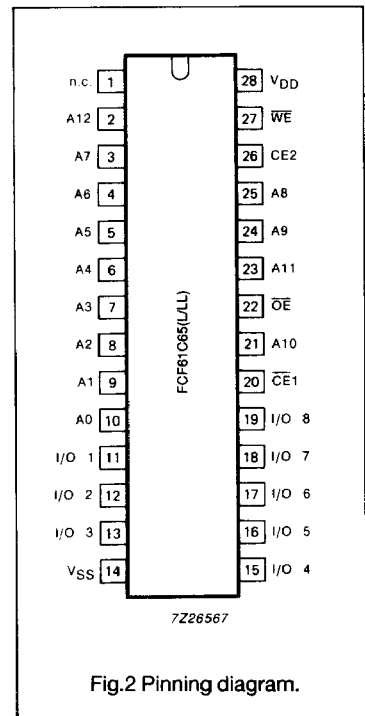
### TRUTH TABLE

$\overline{CE1}$	$CE2$	$\overline{OE}$	$WE$	MODE	$I_{DD}$	I/O PIN	REF. CYCLE
H	X	X	X	not selected	$I_{SB}^*$	HIGH Z	
X	L	X	X	not selected	$I_{SB}^*$	HIGH Z	
L	H	L	H	read	$I_{DD}/I_{DD1}^*$	D OUT	read
L	H	H	L	write	$I_{DD}$	D IN	write
L	H	L	L	write	$I_{DD}$	D IN	write
L	H	H	H	ready-read	$I_{DD}/I_{DD1}^*$	HIGH Z	

\* Including L/LL versions if input levels are CMOS.

### PINNING

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
A12	2	address input
A7 to A0	3 to 10	address inputs
I/O 1 to I/O 3	11 to 13	data inputs/outputs
$V_{SS}$	14	ground
I/O 4 to I/O 8	15 to 19	data inputs/outputs
$\overline{CE1}$	20	chip enable 1
A10	21	address input
$\overline{OE}$	22	output enable
A11, A9, A8	23 to 25	address inputs
$CE2$	26	chip enable 2
$WE$	27	write enable
$V_{DD}$	28	+5 V supply



# 8 K x 8 Fast CMOS low-power static RAM for extended temperature range

## FCF61C65(L/LL)

### DC CHARACTERISTICS

$V_{DD} = 5 V \pm 10\%$ ;  $T_{amb} = -40$  to  $+85$  °C. Typical readings taken at  $V_{DD} = 5 V$ ;  $T_{amb} = 25$  °C. All voltages are referenced to  $V_{SS}$  (0 V) unless otherwise specified. DC characteristics are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{LI}$	input leakage current	$V_I = V_{SS}$ to $V_{DD}$	-2	-	2	$\mu A$
$I_{LO}$	output leakage current	$\overline{CE}1$ or $\overline{OE} = V_{IH}$ or $CE2 = V_{IL}$ ; $V_{I/O} = V_{SS}$ to $V_{DD}$	-2	-	2	$\mu A$
$I_{DD}$	average operating current	cycle time 85 ns; 100% duty factor; note 1 $I_{I/O} = 0$ mA	-	35	60	mA
$I_{DD1}$	DC operating current	$\overline{WE} = V_{IH}$ ; $I_{I/O} = 0$ mA; $f = 0$ Hz	-	3	10	mA
$I_{DDL}$	FCF61C65L only FCF61C65LL only	$\overline{WE} = \text{CMOSH}$ ; $V_I = \text{CMOS}$ ; notes 2 and 3	-	2	200	$\mu A$
$I_{DLL}$			-	0.05	4	$\mu A$
$I_{SB}$	standby current	$\overline{CE}1 = V_{IH}$ or $CE2 = V_{IL}$	-	1.5	3.0	mA
$I_{SBL}$	FCF61C65L only FCF61C65LL only	$\overline{CE}1 = \text{CMOSH}$ and $CE2 = \text{CMOS}$ or $CE2 = \text{CMOSL}$ ; notes 2 and 3	-	2	200	$\mu A$
$I_{SBLL}$			-	0.05	4	$\mu A$
$V_{OL}$	output voltage LOW	$I_{OL} = 4$ mA	-	-	0.4	V
$V_{OL}$	output voltage LOW	$I_{OL} = 20$ $\mu A$	-	-	0.2	V
$V_{OH}$	output voltage HIGH	$I_{OH} = -1$ mA	2.4	-	-	V
$V_{OH}$	output voltage HIGH	$I_{OH} = -20$ $\mu A$	$V_{DD}-0.2$	-	-	V

### Notes to the DC characteristics

- $I_{DD} \leq 55$  mA at a cycle time of 100 ns and  $\leq 50$  mA at a cycle time of 120 ns.
- CMOS = CMOSH:  $V_{DD} - 0.2 V \leq \text{level} \leq V_{DD} + 0.2 V$  or  
CMOSL:  $-0.2 V \leq \text{level} \leq +0.2 V$ .
- At  $T_{amb} = 70$  °C:  $I_{SBL}/I_{DDL} \leq 100$   $\mu A$  max. and  
 $I_{SBL}/I_{DLL} \leq 1$   $\mu A$  max.

### CAPACITANCES

$f = 1$  MHz;  $T_{amb} = 25$  °C (parameters in this table are sampled and not 100% tested).

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$C_I$	input capacitance $\overline{CE}1$ , $CE2$ , $\overline{WE}$ , $\overline{OE}$ all other inputs	$V_I = 0 V$	8	pF
$C_I$		$V_I = 0 V$	7	pF
$C_{I/O}$	input/output capacitance	$V_{I/O} = 0 V$	8	pF

# 8 K x 8 Fast CMOS low-power static RAM for extended temperature range

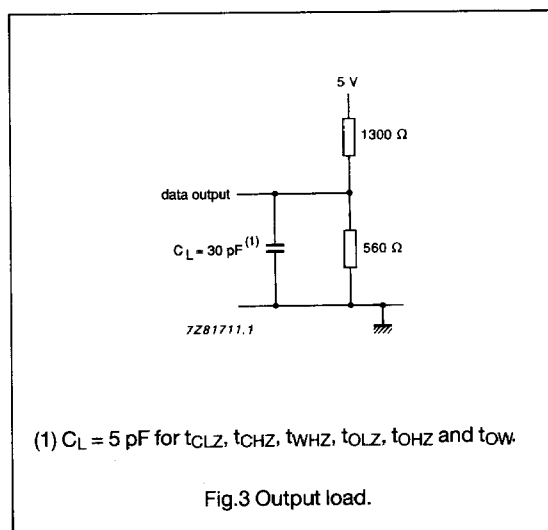
## FCF61C65(L/LL)

### TIMING CHARACTERISTICS

$V_{DD} = 5\text{ V} \pm 10\%$ ;  $T_{amb} = -40$  to  $+85\text{ }^\circ\text{C}$ ; inputs levels = 0.4 to 2.4 V, input rise and fall times = 5 ns; input and output timing reference levels = 1.5 V and output loading as in Figure 3; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
<b>Read cycle</b>					
$t_{RC}$	read cycle time		85	-	ns
$t_{AA}$	address access time		-	85	ns
$t_{ACE}$	chip enable access time		-	85	ns
$t_{OE}$	output enable access time		-	40	ns
$t_{CLZ}$	chip enable to output LOW Z	note 6	5	-	ns
$t_{OLZ}$	output enable to output LOW Z	note 6	5	-	ns
$t_{CHZ}$	chip disable to output HIGH Z	note 6	-	35	ns
$t_{OHZ}$	output disable to output HIGH Z	note 6	-	35	ns
$t_{OH}$	output hold time		10	-	ns
<b>Write cycle</b>					
$t_{WC}$	write cycle time		85	-	ns
$t_{CW}$	chip enable to end of write	note 11	70	-	ns
$t_{AW}$	address valid to end of write		70	-	ns
$t_{AS}$	address set-up time		0	-	ns
$t_{WP}$	write pulse width	note 9	40	-	ns
$t_{WR}$	write recovery time	note 10	5	-	ns
$t_{WHZ}$	write enable to output HIGH Z	note 16	-	35	ns
$t_{DW}$	data to write time overlap		35	-	ns
$t_{DH}$	data hold from write time		5	-	ns
$t_{OW}$	end of write to output LOW Z	note 16	5	-	ns

### Output load



# 8 K x 8 Fast CMOS low-power static RAM for extended temperature range

## FCF61C65(L/LL)

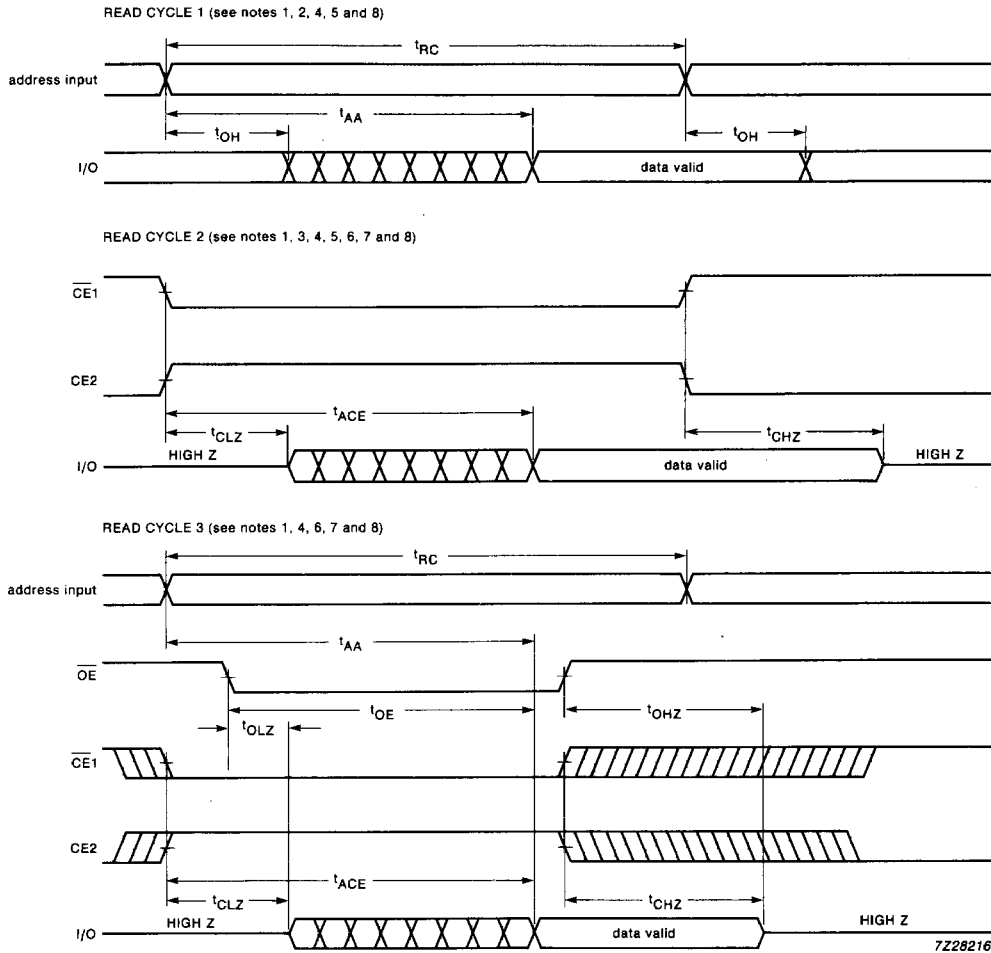


Fig.4 Read cycle timing.



**8 K x 8 Fast CMOS low-power static RAM for extended temperature range**

**FCF61C65(L/LL)**

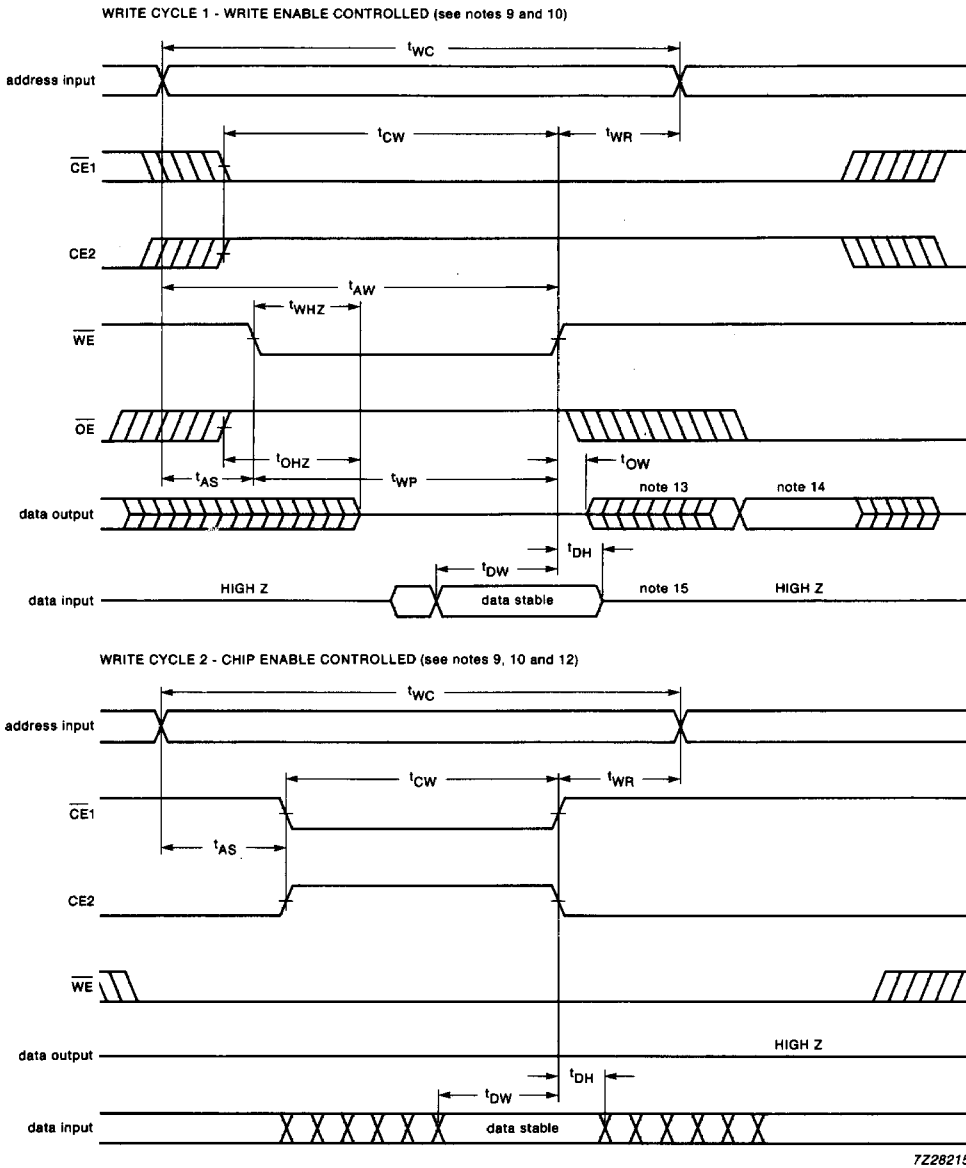


Fig.5 Write cycle timing.

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**8 K x 8 Fast CMOS low-power static RAM for extended temperature range**

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**FCF61C65(L/LL)****Notes to the timing characteristics****Read cycle** (see Fig.4)

1.  $\overline{WE}$  is HIGH for read cycle.
2. Device is continuously selected,  $\overline{CE1}$  is LOW and CE2 is HIGH.
3. Address is valid prior to or coincident with  $\overline{CE1}$  LOW or CE2 HIGH transition.
4. When  $\overline{CE1}$  is LOW and CE2 HIGH, the address inputs may not be floating.
5.  $\overline{OE}$  is LOW.
6.  $C_L = 5$  pF for  $t_{CLZ}$ ,  $t_{CHZ}$ ,  $t_{OLZ}$ , output transition measured at  $\pm 200$  mV from preceding steady state. These parameters are sampled and not 100% tested.
7.  $t_{CLZ}$  and  $t_{ACE}$  are measured from the last  $\overline{CE1}$  going LOW or CE2 going HIGH.  $t_{CHZ}$  is measured from the first of  $\overline{CE1}$  going HIGH or CE2 going LOW.
8. If D OUT in two consecutive read cycles is the same, D OUT remains stable.

**Write cycle** (see Fig.5)

9. A write occurs during an overlap of LOW  $\overline{CE1}$ , a HIGH CE2 and a LOW  $\overline{WE}$ .
10.  $t_{WR}$  is measured from the earlier of CE2 going to LOW or  $\overline{CE1}$  or  $\overline{WE}$  going HIGH at the end of a write cycle.
11. If the  $\overline{CE1}/CE2$  transition occurs simultaneously to or after the  $\overline{WE}$  LOW transition the outputs remain in a high impedance state.
12.  $\overline{OE}$  is continuously LOW.
13. D OUT is in the same phase as the write data of this write cycle.
14. D OUT is the read data of the next address.
15. If  $\overline{CE1}$  is LOW (CE2 is HIGH) and I/O pins are in the output state during this period then input data signals of opposite phase to the outputs must not be applied.
16.  $C_L = 5$  pF for  $t_{WHZ}$  and  $t_{OW}$ , measured at  $\pm 200$  mV from steady state. These parameters are sampled and not 100% tested.

# 8 K x 8 Fast CMOS low-power static RAM for extended temperature range

## FCF61C65(L/LL)

### DATA RETENTION CHARACTERISTICS FOR LOW POWER/STANDBY MODE

(FCF61C65L/LL only)

 $T_{amb} = -40$  to  $+85$  °C;  $I_{DRL/LL}$  measurements are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supply</b>						
$V_{DR}$	supply voltage for data retention	$\overline{CE1} = \text{CMOSH}$ or $CE2 = \text{CMOSL}$ with other $V_i = \text{CMOS}$ ; note 1	2.0	-	5.5	V
$I_{DRL}$ $I_{DRL}$	supply current during data retention FCF61C65L only FCF61C65LL only	$V_{DR} = 3$ V; $CE2 = \text{CMOSL}$ ; other $V_i = \text{CMOS}$ or $\overline{CE1} = \text{CMOSH}$ ; other $V_i = \text{CMOS}$ note 2 note 2	- -	2 0.05	100 4	$\mu\text{A}$ $\mu\text{A}$
<b>Timing</b>						
$t_{CDR}$	chip disable to data retention time		0	-	-	ns
$t_R$	recovery time to fully active	note 3	$t_{RC}$	-	-	ns

#### Notes to the data retention characteristics

- CMOS = CMOSH:  $V_{DR} - 0.2 \text{ V} \leq \text{level} \leq V_{DR} + 0.2 \text{ V}$  or  
CMOSL:  $-0.2 \text{ V} \leq \text{level} \leq +0.2 \text{ V}$ .
- At  $T_{amb} = 70$  °C:  $I_{DRL} \leq 50 \mu\text{A}$  and  $I_{DRL} \leq 1 \mu\text{A}$ .
- $t_{RC}$  = read cycle time.

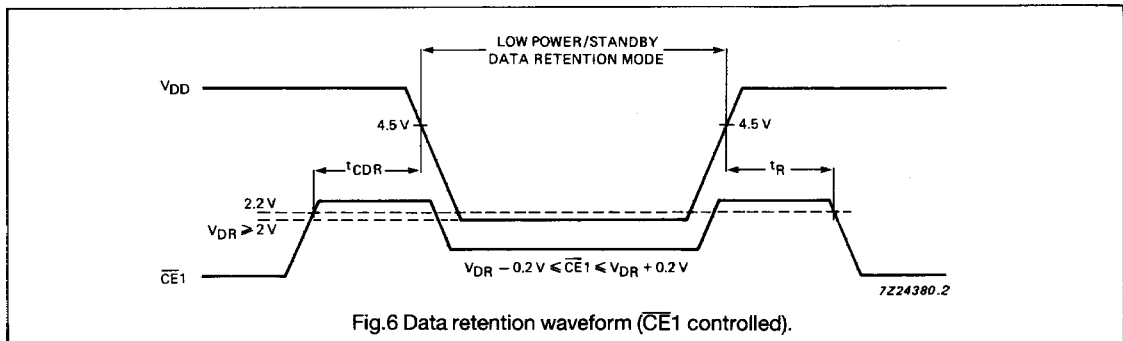


Fig.6 Data retention waveform ( $\overline{CE1}$  controlled).

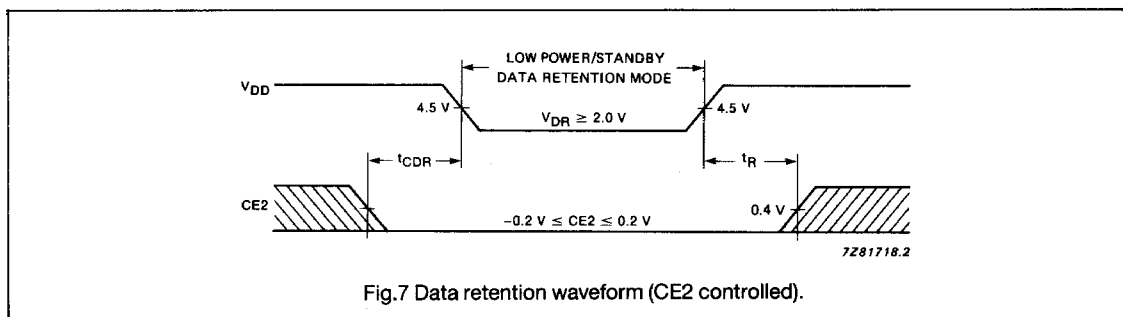


Fig.7 Data retention waveform ( $CE2$  controlled).